TYPICAL DEVICE CHARACTERISTICS

MAXIMUM RATINGS @ 25°C Unless Otherwise Specified							
PARAMETER	SYMBOL	VALUE	UNITS				
Peak Pulse Power (tp = 8/20μs) - See Figure 1	P _{pp}	500	Watts				
Operating Temperature	T _L	-55 to 150	°C				
Storage Temperature	T _{stg}	-55 to 150	°C				
Continuous Power Dissipation	P _{PC}	1000	mW				
Maximum Forward Voltage @ 10mA (Note 1)	V _F	1.1	Volts				
NOTES	'						

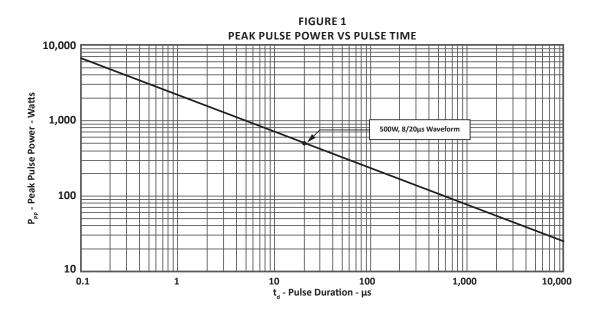
NOTES

1. Measured between pins 8 or 5 to 1, 2, 3, 4, 6 and 7.

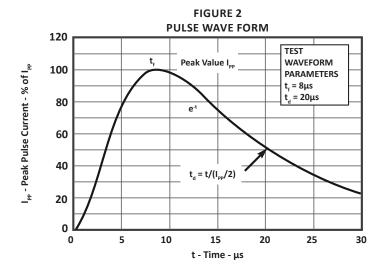
ELECTRICAL CHARACTERISTICS PER LINE @ 25°C Unless Otherwise Specified									
PART NUMBER	DEVICE MARKING	RATED STAND-OFF VOLTAGE V _{wm} VOLTS	MINIMUM BREAKDOWN VOLTAGE @1mA V _(BR) VOLTS	MAXIMUM CLAMPING VOLTAGE (Fig. 2) @I _p = 1A V _c VOLTS	MAXIMUM LEAKAGE CURRENT @V _{wm} I _D μΑ	MAXIMUM CAPACITANCE (Note 1) (Fig. 6) @0V, 1MHz C _{J(SD)} pF			
PSRDA3.3-4	PRA	3.3	4.0	6.5	125	5			
PSRDA05-4	PRB	5.0	6.0	9.8	20	5			
PSRDA12-4	PRD	12.0	13.3	19.0	1	5			
PSRDA15-4	PRE	15.0	16.7	24.0	1	5			

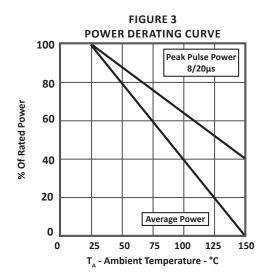
NOTES

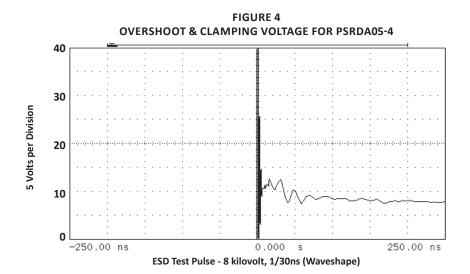
1. Capacitance measured at $V_{WM} = V_{CC}$ connected between I/O pins to pin 8 and 5 (Gnd). $V_R = V_{WM}$ @ 1MHz. As shown in Figure 6, REF1 is connected to ground, REF2 is connected to + $V_{CC'}$ and input applies to $V_{CC} = 5V$, $V_{SIGN} = 30$ mV, F = 1MHz



TYPICAL DEVICE CHARACTERISTICS







TYPICAL DEVICE CHARACTERISTICS

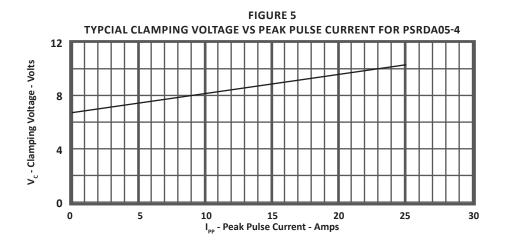
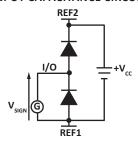
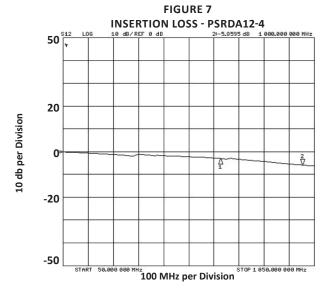
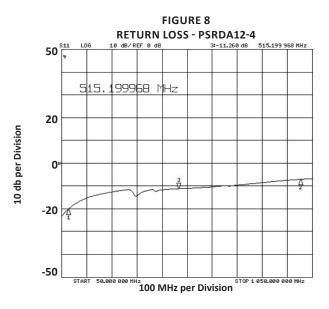


FIGURE 6
INPUT CAPACITANCE CIRCUIT

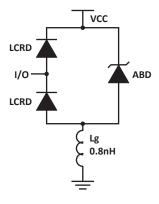






SPICE MODEL

FIGURE 1 SPICE MODEL



ABD - Avalanche Breakdown Diode (TVS) LCRD: Low Capacitance Rectifier Diode Lg - Lead Inductance

TABLE 1 - SPICE PARAMETERS							
PARAMETER	UNIT	ABD(TVS)	LCRD				
BV	V	See Table 2	200				
IBV	μΑ	1	0.01				
C _{jo}	pF	See Table 2	5				
I _s	А	See Table 2	1E-13				
Vj	V	0.6	0.6				
М	-	0.33	0.33				
N	-	1	1				
R _s	Ohms	See Table 2	0.31				
TT	S	1E-8	1E-9				
EG	eV	1.11	1.11				

TABLE 2 - ABD SPECIFIC SPICE PARAMETERS								
PART NUMBER	PART NUMBER B _v (VOLTS) C _{io} (pF) I _s (AMPS)							
PSRDA3.3-4	4.0	438	1E-11	0.21				
PSRDA05-4	6.0	284	1E-11	0.14				
PSRDA12-4	13.3	123	1E-11	0.4				
PSRDA15-4	16.7	102	1E-11	0.52				

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APPLICATION INFORMATION

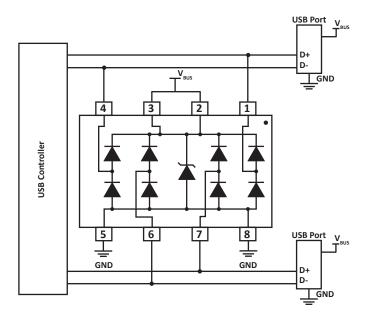


FIGURE 1 - DIFFERENTIAL MODE USB PROTECTION

Circuit connectivity is as follows:

- Pins 1, 2, 4, 6 and 7 connected to the datalines.
- Pin 5 and 8 connected to ground.
- Pins 2 and 3 connected to the databus.

CIRCUIT BOARD RECOMMENDATIONS

Circuit board layout is critical for electromagnetic compatibility protection. The following guidelines are recommended:

- The protection device should be placed near the input terminals or connectors, the device will divert the transient current immediately before it can be coupled into the nearby traces.
- The path length between the TVS device and the protected line should be minimized.
- All conductive loops including power and ground loops should be minimized.
- The transient current return path to ground should be kept as short as possible to reduce parasitic inductance.
- Ground planes should be used whenever possible. For multilayer PCBs, use ground vias.



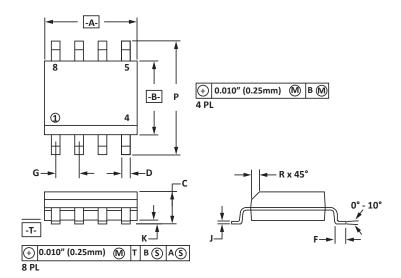


SO-8 PACKAGE INFORMATION

OUTLINE DIMENSIONS							
DIM	MILLIN	IETERS	INCHES				
	MIN	MAX	MIN	MAX			
Α	4.80	5.00	0.189	0.196			
В	3.80	4.00	0.150	0.157			
С	1.35	1.75	0.054	0.068			
D	0.35	0.49	0.014	0.019			
F	0.40	1.25	0.016	0.049			
G	1.27	BSC	0.05	BSC			
J	0.18	0.25	0.007	0.009			
K	0.10	0.25	0.004	0.008			
Р	5.80	6.20	6.20 0.229				
R	0.25	0.50	0.010	0.019			

NOTES

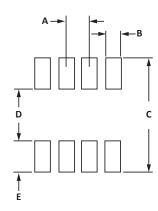
- 1. -T- = Seating plane and datum surface.
- 2. Dimensions "A" and "B" are datum.
- 3. Dimensions "A" and "B" do not include mold protrusion.
- 4. Maximum mold protrusion is 0.015" (0.380mm) per side.
- 5. Dimensioning and tolerances per ANSI Y14.5M, 1982.
- 6. Dimensions are exclusive of mold flash and metal burrs.



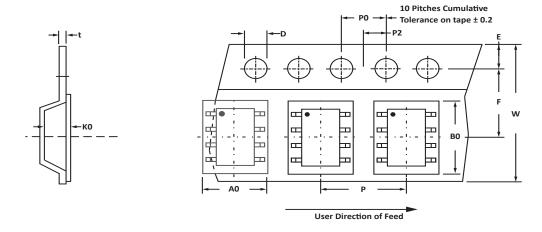
PAD LAYOUT DIMENSIONS							
DIM	MILLIN	IETERS	INCHES				
DIM		MAX	MIN	MAX			
А	1.14	1.40	0.045	0.055			
В	0.64	0.89	0.025	0.035			
С	6.22	-	0.245	-			
D	3.94	4.17	0.155	0.165			
Е	1.02	1.27	0.040	0.050			

NOTES

1. Controlling dimension: inches.



TAPE AND REEL



SPECIFICATIONS												
REEL DIA.	TAPE WIDTH	A0	В0	ко	D	E	F	w	P0	P2	Р	tmax
178mm (7")	12mm	6.50 ± 0.10	5.40 ± 0.10	2.00 ± 0.10	1.50 ± 0.10	1.75 ± 0.10	5.50 ± 0.05	12.00 ± 0.30	4.00 ± 0.12	2.00 ± 0.10	8.00 ± 0.10	0.25

NOTES

- 1. Dimensions are in millimeters.
- 2. Surface mount product is taped and reeled in accordance with EIA-481.
- 3. Suffix T7 = 7" Reel 1,000 pieces per 12mm tape.
- 4. Suffix T13 = 13" Reel 2,500 pieces per 12mm tape.
- 5. Bulk product shipped in tubes of 98 pieces per tube.
- 6. Marking on Part marking code (see page 2), date code, logo and pin one defined by dot on top of package.

ORDERING INFORMATION								
BASE PART NUMBER (xx = Voltage)	LEADFREE SUFFIX	TAPE SUFFIX	QTY/REEL	REEL SIZE	TUBE QTY			
PSRDAxx-4	-LF	-T7	1,000	7"	98			
PSRDAxx-4	-LF	-T13	2,500	13"	98			
This device is only available in	This device is only available in a Lead-Free configuration.							

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COMPANY INFORMATION

COMPANY PROFILE

In business more than 25 years, ProTek Devices™ is a privately held semiconductor company. The company offers a product line of overvoltage protection and overcurrent protection components. These include transient voltage suppressor array (TVS arrays) avalanche breakdown diode, steering diode TVS array and electronics SMD chip fuses. These components deliver circuit protection in electronic systems from numerous overvoltage and overcurrent events. They include lightning; electrostatic discharge (ESD); nuclear electromagnetic pulses (NEMP); inductive switching; and electromagnetic interference (EMI) / radio frequency interference (RFI). ProTek Devices also offers LED wafer die for ESD protection and related high frequency products. ProTek Devices is ISO 9001:2015 certified.

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